	Hit	Search Text	DBs
	s	Search Text	DBS
1	2	(immersion near14 lithography) and ((workpiece or substrate or wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or sensitive) same (source or radiation or light) same (modulat\$4 or (spatial near14 modulat\$4) or SLM) same (mask or photomask or reticle or pattern\$3) same (immersi\$3 near6 (fluid\$4 or liquid or medium)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
2	2	sensitive) same (source or radiation or light) same (mask or photomask or reticle or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
3	7	(immersion near14 lithography) and ((workpiece or substrate or wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or sensitive) same (source or radiation or light) same	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hit	Search Text	DBs
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4	8	photoresist or resist or sensitive) same (source or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
5	9	((immersion near14 lithography) or (liquid near9 immersion)) and ((workpiece or substrate or wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or sensitive) same (source or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
6	13	((immersion near14 lithography) or (liquid near9 immersion)) and ((workpiece or substrate or wafer) same (photosensitive or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hit	Search Text	DBs
7	19	water) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
8	71	photoresist or resist or sensitive)) and ((substrate or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
9	55	((immersion near14 lithography) or (liquid near9 immersion)) and ((workpiece or substrate or wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or sensitive)) and ((substrate or wafer or workpiece) same	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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10	45	pnotoresist or resist or sensitive)) and ((substrate or wafer or workpiece) same	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
11	3	((immersion near14 lithography) or (liquid near9 immersion near14 (system or apparatus or method))) and ((workpiece or substrate or wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or sensitive)) and ((substrate or wafer or workpiece) same	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hit s	Search Text	DBs
12	3	(light\$3 near5 sensitive) or photoresist or resist or sensitive) and ((substrate or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
13	59	water) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or sensitive)) and ((substrate or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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14	58	photoresist or resist or sensitive) or sensitive) and ((substrate or wafer or workpiece) same	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
15	1	((immersion near14 lithography) or (liquid near9 immersion near14 (system or apparatus or method))) and ((workpiece or substrate or wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or sensitive)) and ((substrate or wafer or workpiece) same ((fluid\$4 or liquid or medium)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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16		sensitive)) and ((substrate or	IBM_TDB
17	129	wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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18	12	wafer) same (photosensitive or (light\$3 near5 sensitive) or photoresist or resist or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB